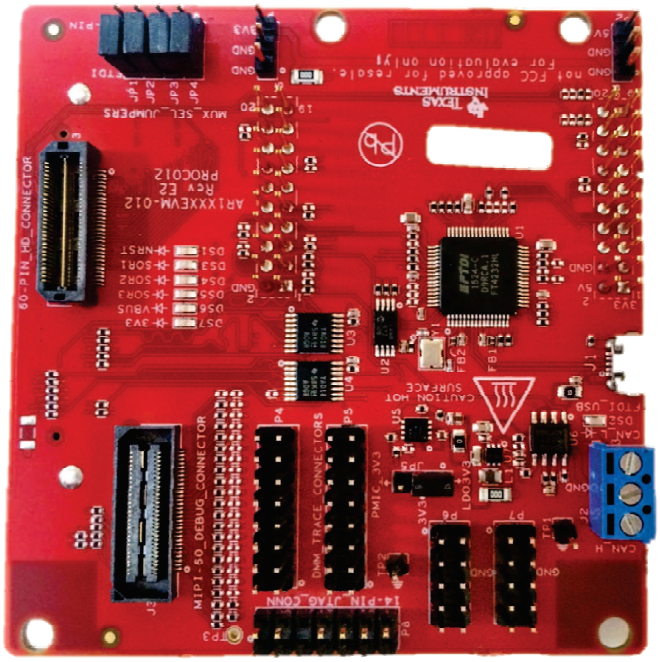
User's Guide
SWRU506–May 2017

MMWAVE-DEVPACK



MMWAVE-DEVPACK

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1 Getting Started

1.1 Introduction

The MMWAVE-DEVPACK is an add-on board used with TIs mmwave sensor EVMs (1243BOOST, 1443BOOST, and 1642BOOST) to provide more interfaces and PC connectivity to the mmwave sensor EVM. It provides an interface for the Radar Studio tool to configure the Radar device and capture the raw ADC data using a capture card, such as the TSW1400.

Key features:

- 120-pin connector to interface with the TSW1400 EVM.
- 20-pin LaunchPad connectors for all the digital controls from the Radar EVM.
- 60-pin high-density (HD) connector for the high-speed ADC data over CSI or LVDS interface and emulator signals from the BoosterPack.
- Onboard FTDI chip to provide PC interface for SPI, GPIO controls, UART loggers.
- Powered over the micro USB connector.
- 60-pin MIPI connector for JTAG trace (for the 16xx device only).
- Header for DMM interface (for the 16xx device only).
- Second CAN connector (for the 16xx device only).

1.2 Kit Contents

- MMWAVE-DEVPACK
- Micro USB cable to connect to PC.
- Samtec cable to connect the 60-pin high-density connectors of the DevPack and BoosterPack (PN HQCD-030-02.00-SEU-TBR-1).

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2 Hardware

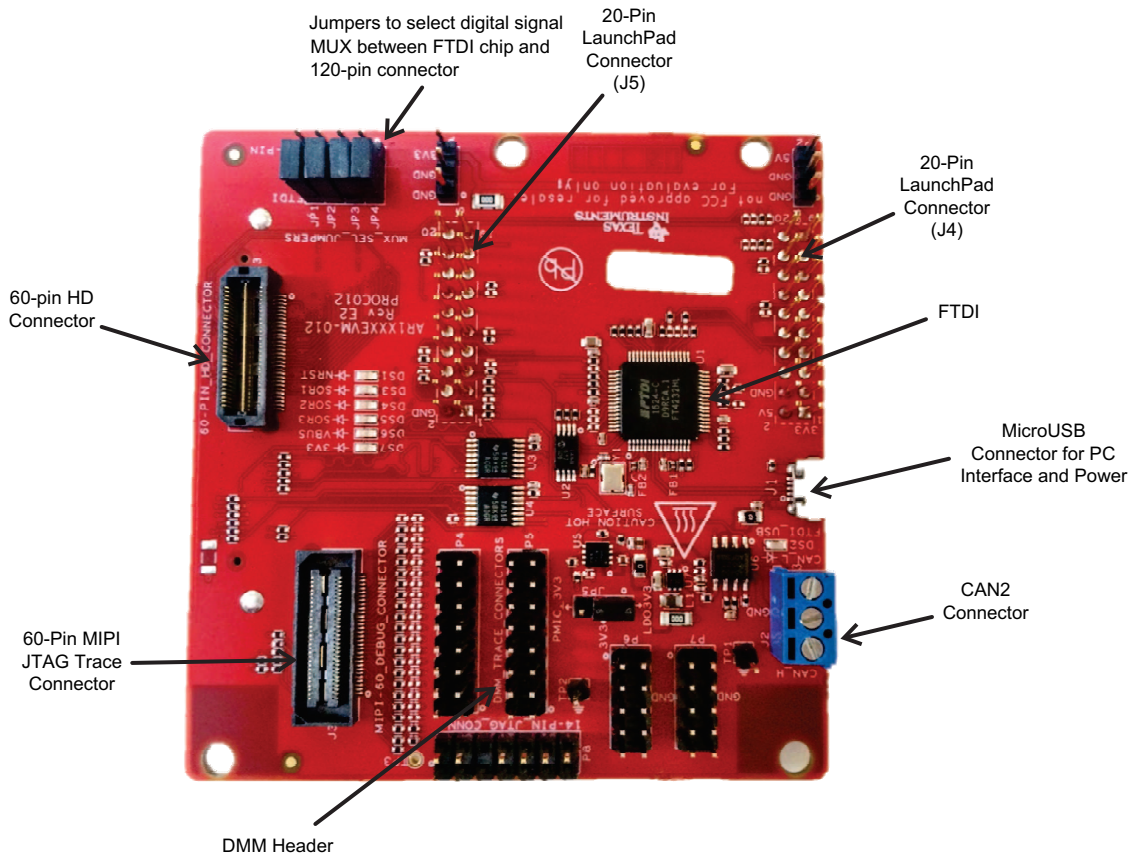


Figure 1. EVM Front View

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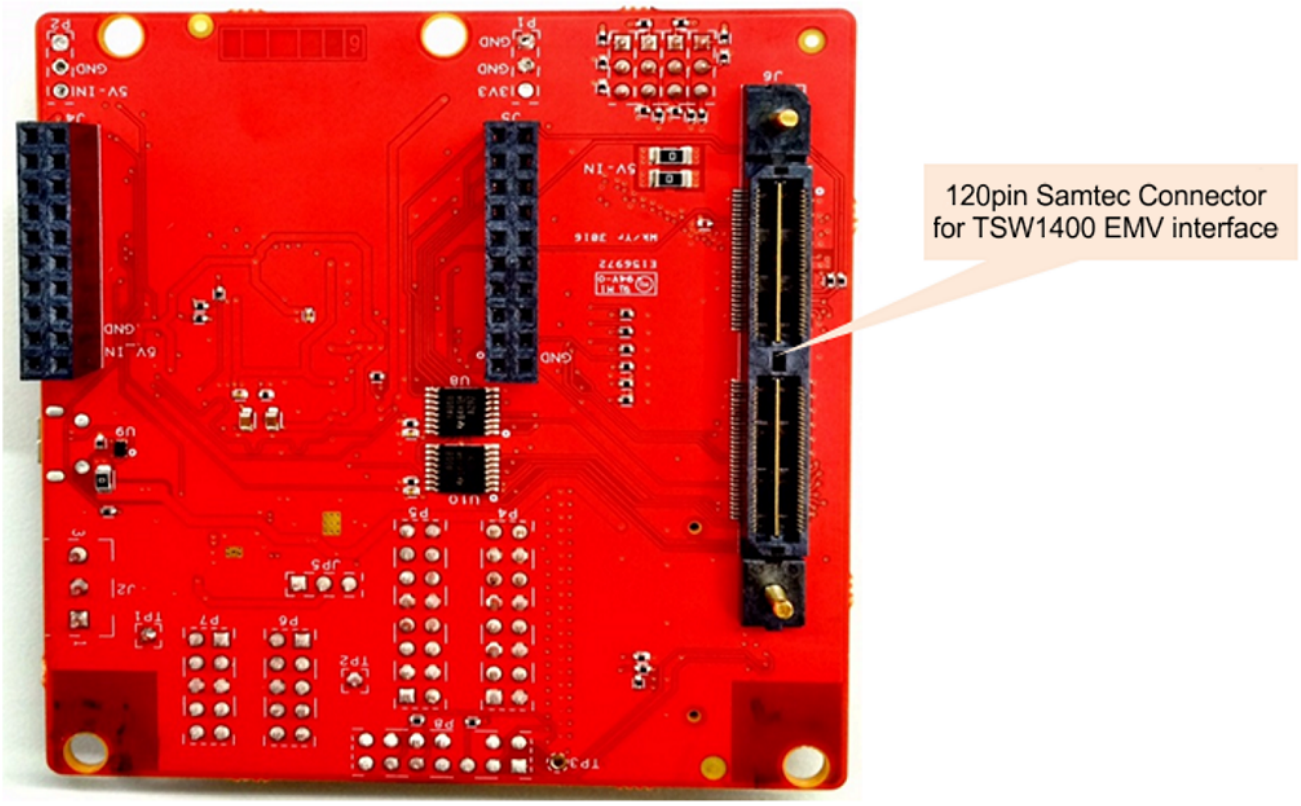


Figure 2. EVM Rear View

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2.1 Block Diagram

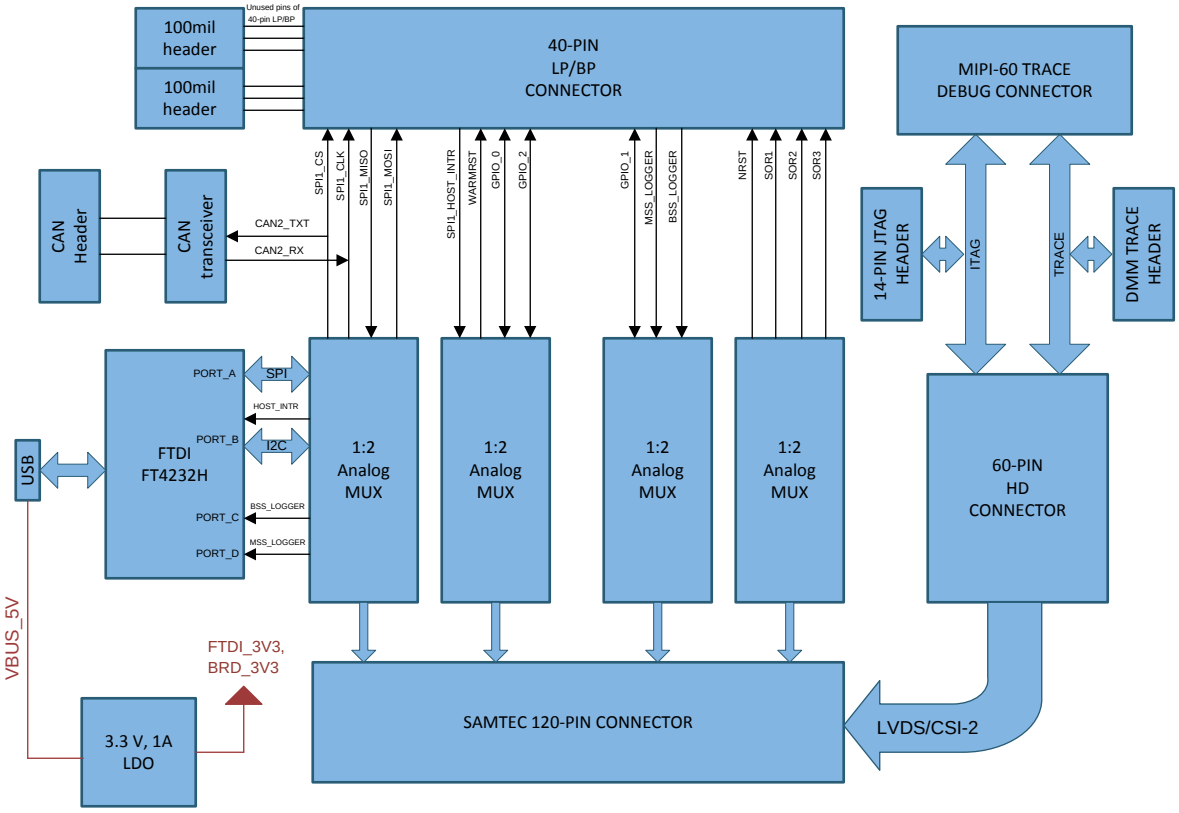


Figure 3. Block Diagram

2.2 Connecting the mmwave Sensor BoosterPack to the DevPack

The two boards connect directly over the 20-pin LaunchPad connectors, and the 60-pin HD connectors are connected using a separate Samtec cable (HQCD-030-02.00-SEU-TBR-1). The BoosterPack is always placed above the DevPack. The connectors do not have a key to prevent the misalignment of the pins or reverse connection. Thus, ensure that reverse mounting does not occur. While connecting the BoosterPack to DevPack, ensure the pin 1 orientation is correct by matching the 3V3 and 5-V signal marking on both the boards. Figure 4 illustrates the connection orientation.

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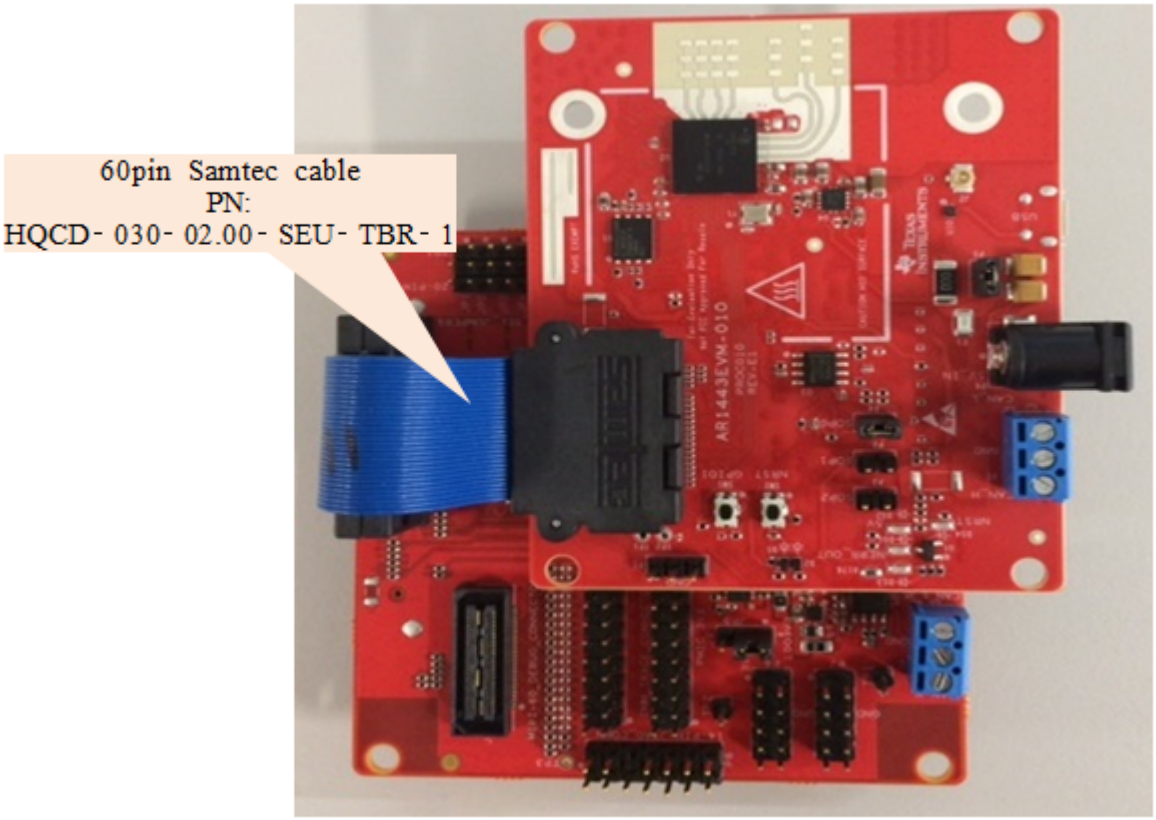


Figure 4. Example BoosterPack Connection with DevPack

2.3 Power Connections

The DevPack is powered by the micro USB cable. However, the onboard LDO is enabled only when the BoosterPack connected to the DevPack is powered. This is to prevent the DevPack from powering up before the BoosterPack. This is done by looking for 3.3 V on the PGOOD_3V3 line available J4 connector, pin#14.

When the two boards are powered, the VBUS LED (DS6) and 3V3 LED (DS7) glow, as shown in Figure 5.

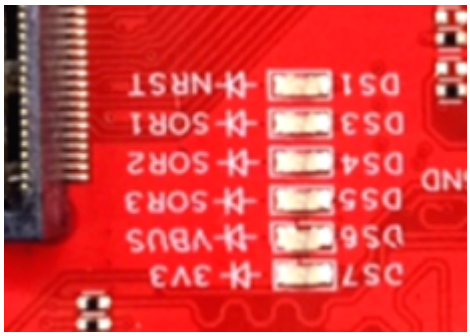


Figure 5. VBUS LED (DS6) and 3V3 LED (DS7)

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2.4 Connectors

2.4.1 20-Pin BoosterPack Connectors (J5 , J4)

The 20-pin BoosterPack connectors mate directly with the mmwave BoosterPack. The orientation of the boards while connected must be ensured by matching the 3V3 and 5-V pin markings on both the boards, as shown in Figure 6.

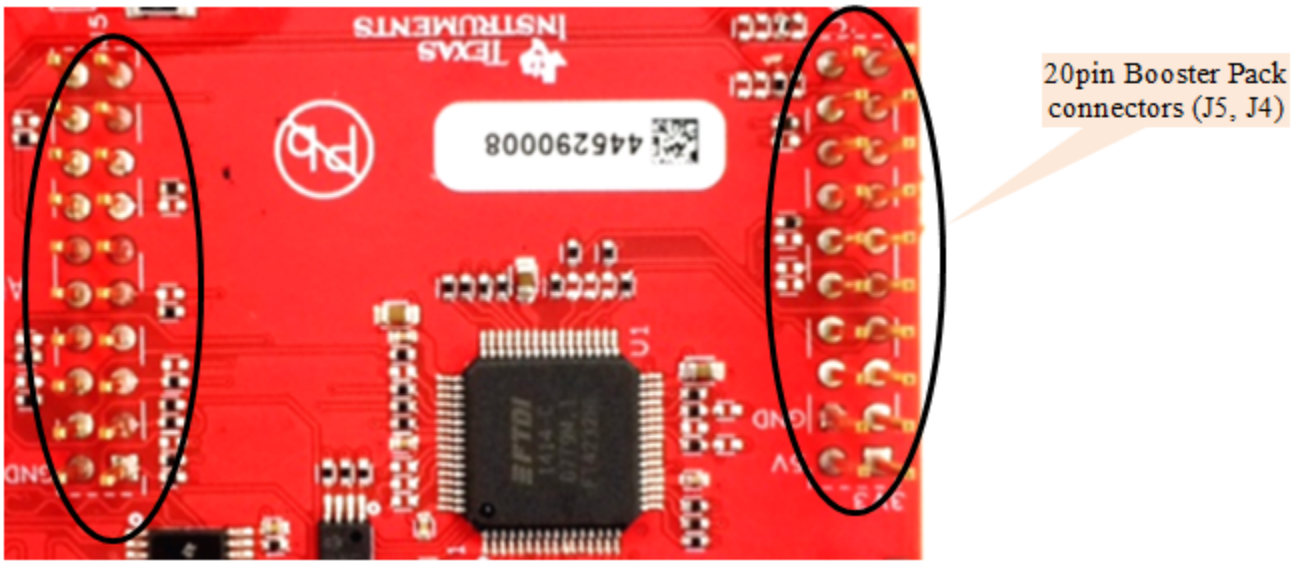


Figure 6. 20-Pin BoosterPack Connectors

2.4.2 60-Pin High Density (HD) Connector (P3)

The 60-pin HD connector (see Figure 7) provides the high-speed CSI/LVDS data, controls signals (SPI , UART, I2C, NRST, NERR, and SOPs), and JTAG debug signals from the BoosterPack. The Trace and DMM interface lines are also available through this connector.



Figure 7. 60-Pin HD Connector

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2.4.3 120-Pin High Density (HD) Connector (J6)

This connector enables interfacing the LVDS signals to the TSW1400 EVM or the CSI, and control signals to the central processor board, as shown in Figure 8.

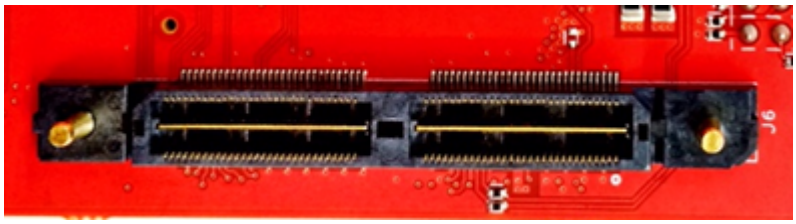


Figure 8. 120-Pin TSW EVM Interface Connector

2.4.4 MIPI 60-Pin JTAG Connector (J3)

This connector provides the standard MIPI 60-pin interface for JTAG and trace capability (trace is available only on the 1642 device), through emulators such as the XDS560pro (see Figure 9). To use this interface, tlhe JTAG lines to the onboard emulator (XDS110) on the mmwave BoosterPack must be disconnected. This is done by removing the resistors R69, R70, R71, and R30 from the mmwave BOOST boards.

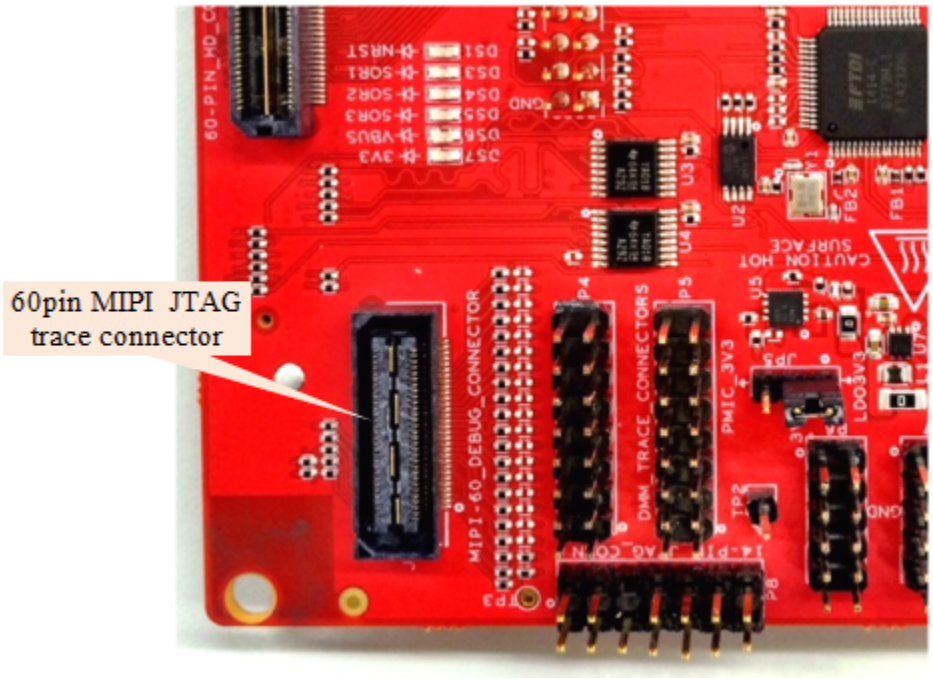


Figure 9. MIPI 60-Pin JTAG Connector

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2.4.5 TI 14-Pin JTAG Connector (P8)

This connector provides a JTAG interface for debug and development, through emulators such as the XDS100 (see Figure 10). To use this interface, the JTAG lines to the onboard emulator (XDS110) on the mmwave BoosterPack must be disconnected. This is done by removing the resistors R69, R70, R71, and R30 on the mmwave BoosterPacks.

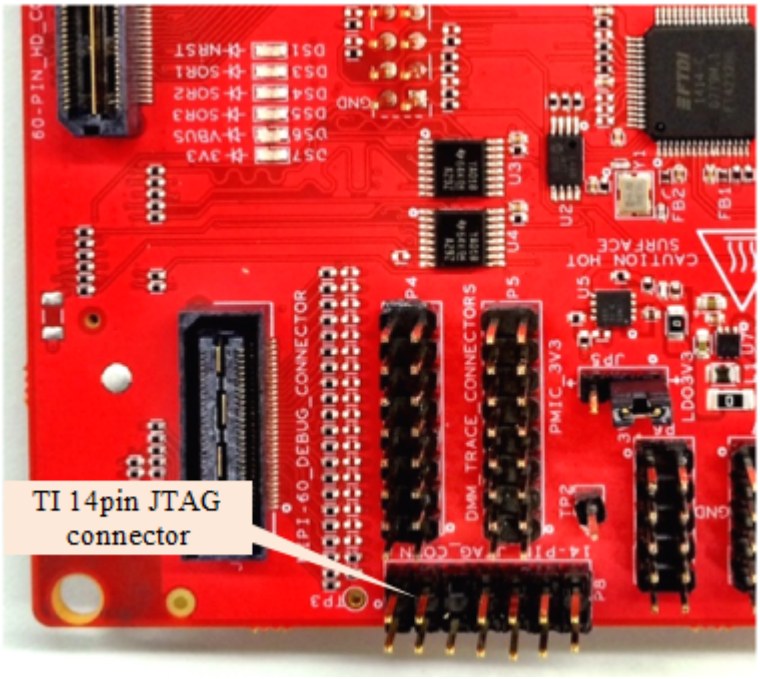


Figure 10. TI 14-Pin JTAG Connector

2.5 PC Connection

Connectivity is provided through the micro USB connector over the onboard FTDI IC. This provides the following interfaces to the PC:

- FTDI Port A -> SPI interface for radar device control using Radar Studio.
- FTDI Port B-> I2C interface and host INTR signal.
- FTDI Port C -> BSS Logger port (for internal debug only), Nrst control, and Nerror signals.
- FTDI Port D -> DSS Logger port (available only on 1642 device), SOP line control signals, and GPIO signals

When the USB is connected for the first time to the PC, Windows® maybe not be able to recognize the device. This is indicated in the device manager with yellow exclamation marks, as shown in Figure 11.

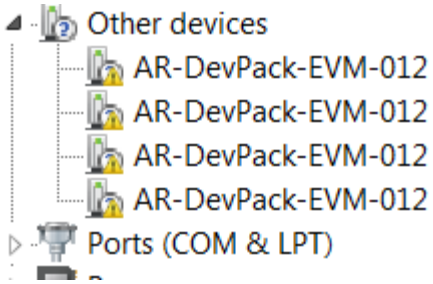


Figure 11. Uninstalled Devices

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To install the devices, download the latest FTDI drivers available in the mmwave SDK package. Right-click on these devices, and update the drivers by pointing to the location where the FTDI drivers were downloaded. This must be done for all four COM ports. When all four COM ports are installed, the device manager recognizes these devices and indicates the COM port numbers, as shown in Figure 12.

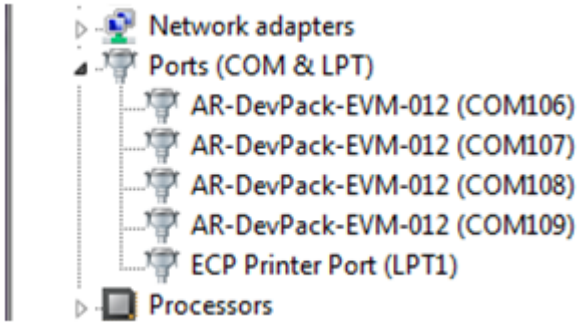


Figure 12. COM Ports After the Driver Installation

2.6 Jumpers and LEDs

2.6.1 MUX Select Jumpers

The digital signals such as SPI, INTR, nRST, GPIOs, and SOP controls, can either go to the FTDI chip (for control from the PC) or to the 120-pin connector (for processor connectivity such as the TDA3). These jumpers are shown in Figure 13.

The jumper position of pin 2-3 connected selects the FTDI path.

The jumper position of pin 2-1 connected selects the 120-pin connector path.

JP1 -> selects the path for nRST and SOP signals.

JP2 -> selects the path for loggers and GPIO_1 signals.

JP3 -> selects the path for INTR, warmrst, GPIO_0, and GPIO_2 signals.

JP4 -> selects the path for SPI signals.



Figure 13. MUX Select Jumpers

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2.6.2 LEDs

Table 1 lists the details of the LEDs. Figure 14 shows the LEDs on the board.

Table 1. LEDs

Ref	Color	Usage
DS7	Red	3V3 supply indication
DS6	Red	5-V supply indication (from USB bus)
DS5	YELLOW	SOR3 (SOP0) state
DS4	YELLOW	SOR2 (SOP1) state
DS3	YELLOW	SOR1 (SOP2) state
DS1	YELLOW	NRST



Figure 14. LEDs

2.7 Design Files and Software Tools

2.7.1 Hardware

The schematics and assembly files can be found here.

2.7.2 Required Software Tools

1. The latest mmwave SDK can be found here.
2. The RF testing tool Radar Studio and its dependencies can be found as part of the DFP package.

3 Interfacing With Other Platforms

3.1 Radar Studio Interface

To control the radar device from Radar Studio, both the mmwave BoosterPack and the DevPack must be powered and connected to the PC using the micro USB cable. The UART used to download the firmware is accessed from the XDS110 device on the mmwave BoosterPack. The SPI interface used to control the radar device, SOP controls, and nRST control is performed from the FTDI chip on the DevPack.

For details on the usage of Radar Studio, refer to the RadarStudio User's Guide.pdf, which is part of the DFP package.

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3.1.1 Jumper Setting on DevPack

To mux all the digital controls to FTDI, the MUX control jumpers on the DevPack should be set as shown in Figure 15 (all connecting pin 2-3).



Figure 15. MUX Control Jumpers

3.1.2 DevPack and BoosterPack Connections

Refer to Section 2.2 for the connection details. The BoosterPack is powered by the 5-V supply. The micro USB cables for both the DevPack and the BoosterPack must be connected. Refer to Figure 16.

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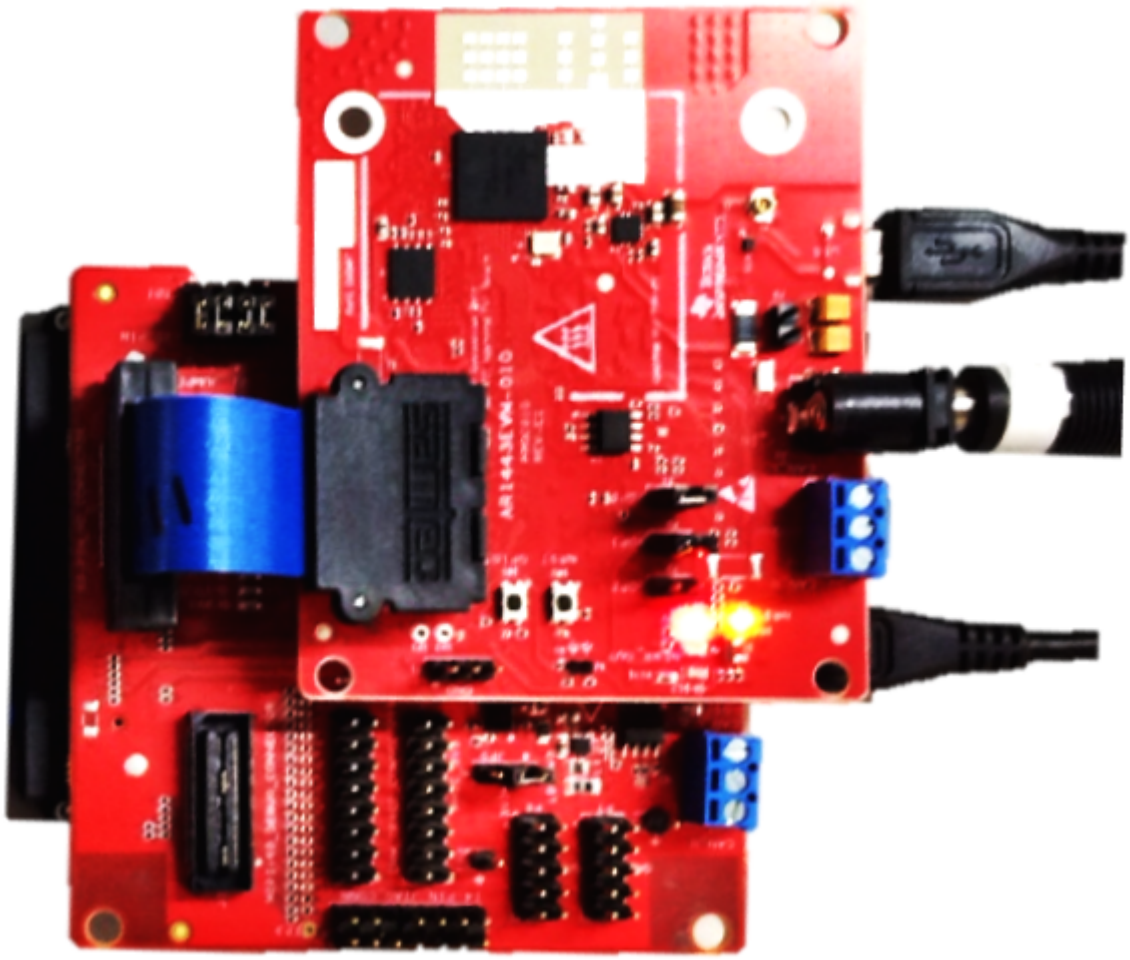


Figure 16. Example DevPack–BoosterPack Connection

3.1.3 COM Port Selection in Radar Studio

The RS232 COM port used in Radar Studio is indicated as XDS110 Class Application/User UART in the device manager, as shown in Figure 17.

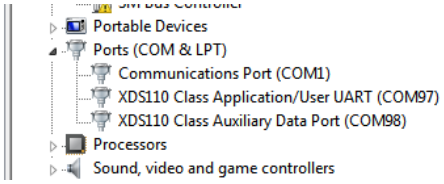


Figure 17. Device Manager

3.2 Interfacing With the High-Speed Data Capture Platform: TSW1400 EVM

The high-speed LVDS data from the radar device can be captured using the TSW1400. For more details on the TSW1400 EVM and ordering details, see the *High Speed Data Capture and Pattern Generation Platform*. To configure this, TSW1400 HSDC Pro software and Radar Studio are required. For the installation and usage of the HSDC Pro tool, refer to the RadarStudio User's Guide.pdf, which is including in the DFP package.

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3.2.1 DevPack and BoosterPack Configuration

The configuration of the DevPack and BoosterPack are the same as mentioned in Section 3.1.

3.2.2 TSW1400 EVM Connection

The TSW1400 EVM must be powered up with a 5-V supply and the mini-USB cable connected to the same PC as the DevPack and BoosterPack. A 120-pin Samtec cable (HQCD-060-08.00-TBL-SBR-1-D) is used to connect the J6 120-pin connector on the DevPack to the J3 ADC input connector on the TSW1400 EVM. Refer to the setup images, Figure 18 and Figure 19. The "08.00" of the cable part number is the length of the cable in inches. The length can be increased accordingly, based on user need, when ordering the cable.

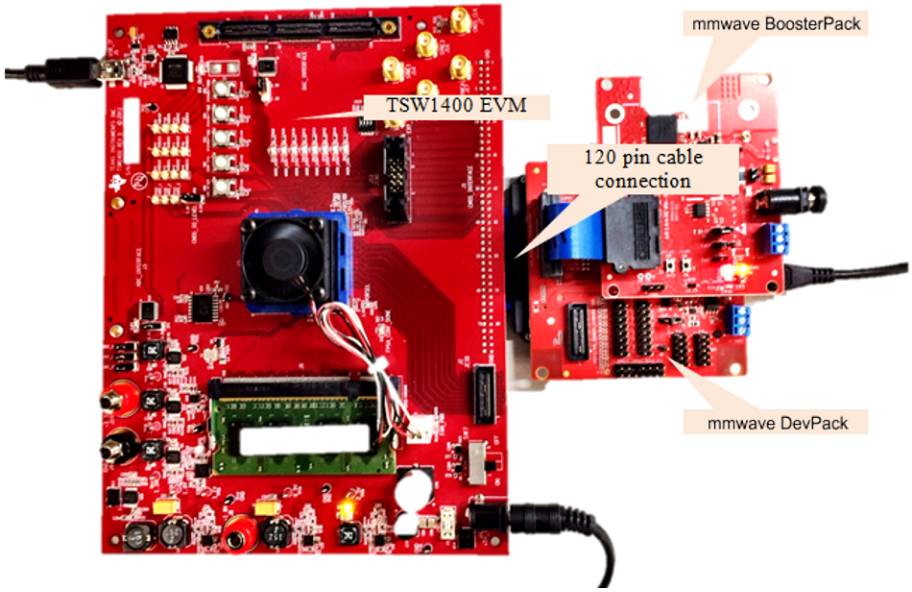


Figure 18. TSW1400 Connection – Front View

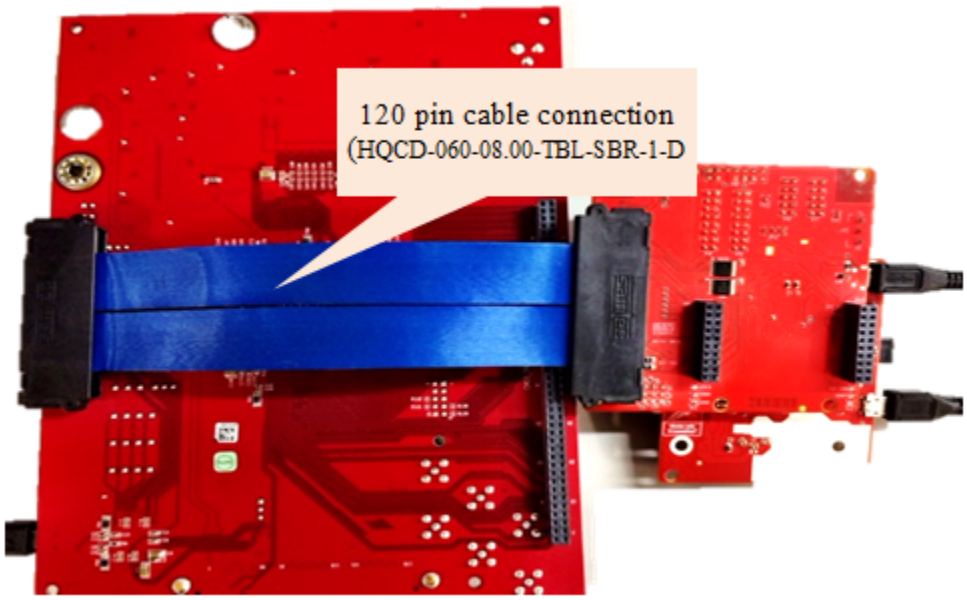


Figure 19. TSW1400 Connection – Rear View

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If the user does not have the 120-pin Samtec cable, the mmwave dev pack can be directly connected to the TSW1400 board, as shown in Figure 20. In this case, the user must ensure that all three boards are properly mechanically supported, to avoid stress on the 120-pin connector. Also, the user must ensure that the fan of the TSW1400 board does not touch anything.

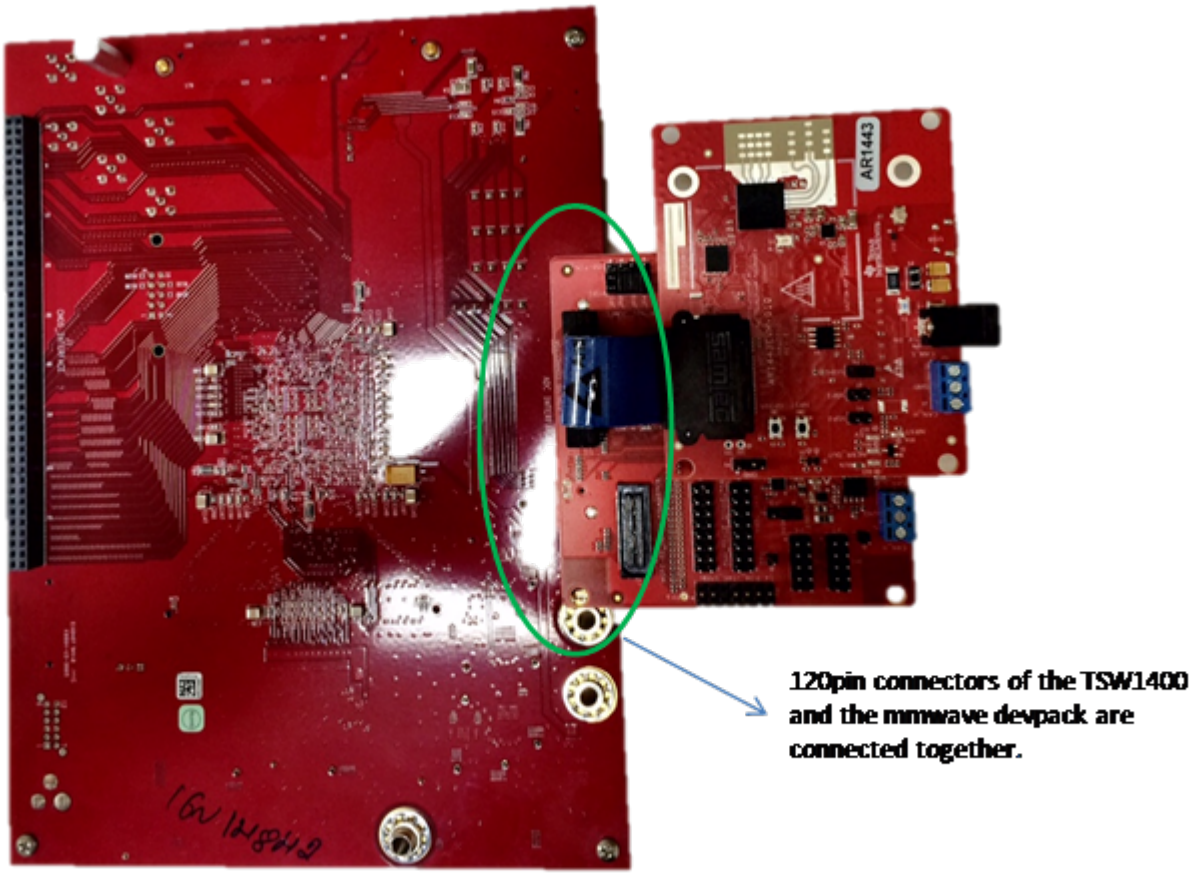


Figure 20. Connecting the mmWave DevPack

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   2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

3 *Regulatory Notices:*

   3.1 *United States*

      3.1.1 *Notice applicable to EVMs not FCC-Approved:*

      FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

      3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

      CAUTION

      This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

      Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

      FCC Interference Statement for Class A EVM devices

      NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

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FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- *Reorient or relocate the receiving antenna.*
- *Increase the separation between the equipment and receiver.*
- *Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.*
- *Consult the dealer or an experienced radio/TV technician for help.*

3.2 *Canada*

3.2.1 *For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247*

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

3.3 *Japan*

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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3.3.3 *Notice for EVMs for Power Line Communication:* Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_02.page
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3.4 *European Union*

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive)*:

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4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

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STANDARD TERMS FOR EVALUATION MODULES (continued)

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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